



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-02-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STU3LN80K5	CLIK*VK80B52	A	3068	2018-02-23
Amount	UoM	Unit type	ST ECOPACK Grade	
310	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DIP	6.1-6.5-2.3	3	Through-hole
Comment	IPAK TO-251		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	2.36	Die / Leadframe	7606
Lead	2.36	Soft solder	7603

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr item Name	CLIK*VK80852				6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.852	mg	supplier	die	Silicon (Si)	7440-21-3		1.780	mg	961123	5742
				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	12419	74
				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	8099	48
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	5400	32
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	540	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.017	mg	9179	55
Leadframe	M-004 Copper and its alloys	184.074	mg	supplier	alloy	Copper (Cu)	7440-50-8		181.496	mg	985995	585471
				supplier	alloy	Iron (Fe)	7439-89-6		0.182	mg	988	587
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.055	mg	299	177
Soft solder	Solder	2.468	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.357	mg	955024	7603
				supplier	solder	Silver (Ag)	7440-22-4		0.062	mg	25122	200
				supplier	solder	Tin (Sn)	7440-31-5		0.049	mg	19854	160
				supplier	wire	Copper (Cu)	7440-50-8		0.116	mg	1000000	374
Encapsulation	M-011 Other inorganic materials	117.787	mg	supplier	mold compound	Silica, vitreous	60676-86-0		103.063	mg	874995	332461
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		4.712	mg	40004	15200
				supplier	mold compound	Epoxy Resin	25068-38-6		3.534	mg	30003	11400
				supplier	mold compound	phenol resin	29690-82-2		5.889	mg	49997	18997
				supplier	mold compound	Carbon black	1333-86-4		0.589	mg	5001	1900
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945